

# Fast Switching Rectifier Die

## NGTD9R120F2

Fast switching low Vf rectifier die for free-wheeling applications.

### Features

- Fast Switching
- Low Vf

### Typical Applications

- Industrial Motor Control
- Solar PV Inverters

### MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	$V_{RRM}$	1200	V
Max Forward Conduction Current	$I_F$	(Note 1)	A
Maximum Junction Temperature	$T_J$	175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Depending on thermal properties of assembly.

### MECHANICAL DATA

Parameter	Value	Unit
Die Size	2900 x 2900	$\mu\text{m}^2$
Die Thickness	10	mils
Wafer Size	150	mm
Top Pad Size (Anode)	2263 x 2263	$\mu\text{m}^2$
Top Metal (Anode)	4 $\mu\text{m}$ AlSi	
Back Metal (Cathode)	2 $\mu\text{m}$ TiNiAg	
Max Possible Chips per Wafer	1535	
Passivation Frontside	Oxide-Nitride	
Reject Ink Dot Size	25 mils	
Recommended Storage Environment: In original container, in dry nitrogen, or temperature of 18–28°C, 30–65%RH	Type: Bare Wafer in Jar Storage time: < 36 months	Type: Die on tape in ring-pack Storage time: < 3 months

### ORDERING INFORMATION

Device	Inking?	Shipping
NGTD9R120F2WP	Yes	Bare Wafer in Jar
NGTD9R120F2SWK	Yes	Sawn Wafer on Tape

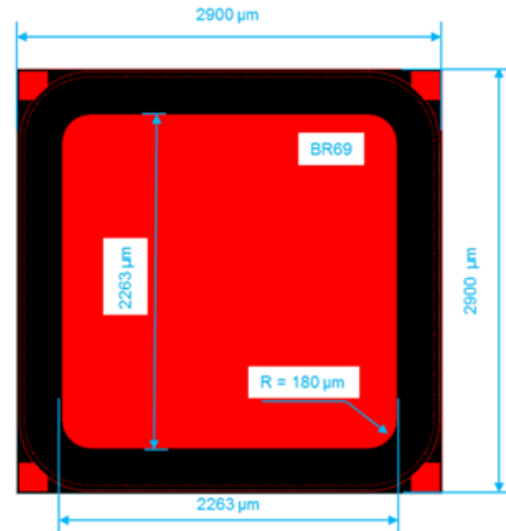
$$V_{RRM} = 1200 \text{ V}$$

$$I_F = \text{Limited by } T_{J(\text{max})}$$

DIOLE DIE



DIE OUTLINE



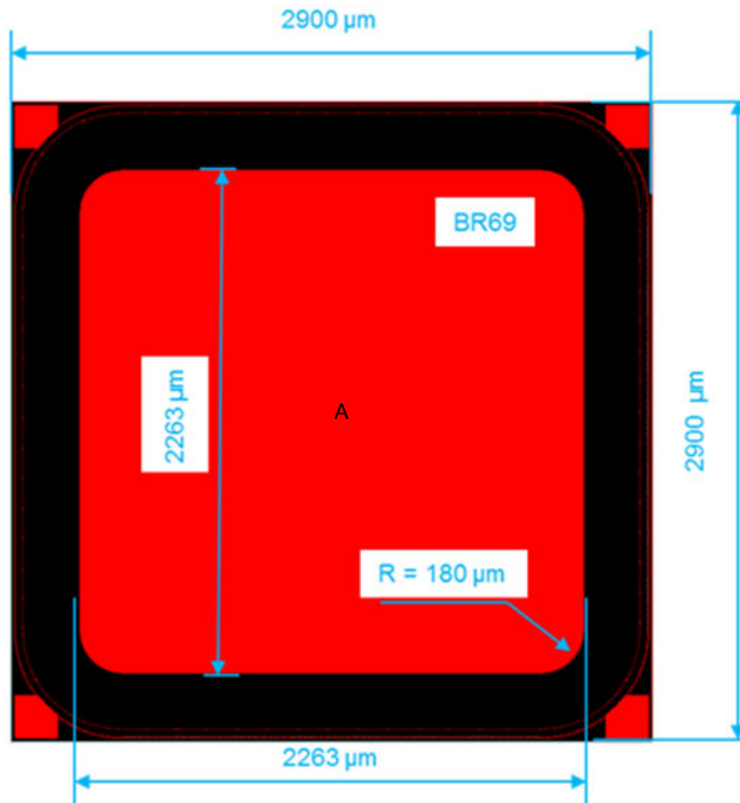
# NGTD9R120F2

## ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Units
<b>STATIC CHARACTERISTICS</b>						
Forward Voltage	$I_F = 15\text{ A}$ , $T_J = 25^\circ\text{C}$	$V_F$		2.0	2.6	V
Reverse Voltage	$I_R = 250\ \mu\text{A}$ , $T_J = 25^\circ\text{C}$	$V_R$	1200			V
Reverse Current	$V_R = 1200\text{ V}$ , $T_J = 25^\circ\text{C}$	$I_R$	-1.0		1.0	$\mu\text{A}$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## DIE LAYOUT



A = Anode pad  
All dimensions in  $\mu\text{m}$

### Further Electrical Characteristic

Switching characteristics and thermal properties are depending strongly on module design and mounting technology and can therefore not be specified for a bare die.

**onsemi**, **Onsemi**, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "**onsemi**" or its affiliates and/or subsidiaries in the United States and/or other countries. **onsemi** owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of **onsemi**'s product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). **onsemi** reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and **onsemi** makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using **onsemi** products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by **onsemi**. "Typical" parameters which may be provided in **onsemi** data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. **onsemi** does not convey any license under any of its intellectual property rights nor the rights of others. **onsemi** products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use **onsemi** products for any such unintended or unauthorized application, Buyer shall indemnify and hold **onsemi** and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that **onsemi** was negligent regarding the design or manufacture of the part. **onsemi** is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Email Requests to: [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**onsemi Website:** [www.onsemi.com](http://www.onsemi.com)

### TECHNICAL SUPPORT

**North American Technical Support:**

Voice Mail: 1 800-282-9855 Toll Free USA/Canada

Phone: 011 421 33 790 2910

**Europe, Middle East and Africa Technical Support:**

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative

